

HEAT SINK ASSEMBLY AND METHOD OF ATTACHING A HEAT SINK TO AN ELECTRONIC DEVICE ON A MOTHERBOARD

Abstract of the Disclosure

5

A heat sink assembly is coupled to a motherboard and an electronic device on the motherboard. The heat sink assembly includes a heat sink with an opening extending through the heat sink, and a pin that extends through the motherboard and the opening in the heat sink to couple the heat sink to the electronic device and the motherboard. A member within the opening in the heat sink is positioned between the heat sink and the pin. A method of securing a heat sink to a motherboard and an electronic device on the motherboard includes thermally coupling a heat sink to an electronic device, securing the heat sink to a motherboard using a pin that extends through an opening in the heat sink, and positioning a member between the pin and the heat sink within the opening in the heat sink.

10

15

"Express Mail" mailing label number: EV 332568547 US
Date of Deposit: June 27, 2003,

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.